

HiDECK® Structural 25, 28 & 30

High Conductivity Structural Floorboard



Product Information

CELLECTA's HiDECK® Structural is a highly conductive structural floorboard ideal for acoustic batten & cradle and batten applications incorporating an underfloor heating system. The board's rapid heat transfer characteristics enables an UFH system to operate more efficiently, providing long term running cost savings.

Product Benefits

- Outstanding acoustic and fire performance
- **Robust Detail** proprietary floorboard for FFT1, 2 & 3
- Low thermal resistance - Perfect for UFH applications
- Suitable for steel, concrete and timber floors
- Directly accepts all types of floor covering, inc. tiles

Technical Data

		HiDECK® Structural		
		25	28	30
Product description	-	Tongue and groove, high density gypsum, low thermal resistance structural floorboard		
Thickness'	mm	25	28	30
Thermal resistance	m ² K/W	0.0625	0.070	0.075
Bearing spacing (45mm wide)	mm	400 (max) centers	400 (max) centers	400 (max) centers
Board dimensions	mm	600 x 1200	600 x 1200	600 x 1200
Weight	kg/m ²	31.25	35.00	37.50
	kg/board	22.50	25.20	27.00
Associated flanking strip required	-	YELOfon ES5/120	YELOfon ES5/120	YELOfon ES5/120

Third Party Accreditation and Approvals



Environmental Credentials

